

SEP 14 2006

Appl. No. 10/770,737  
Reply to Final office action of July 14, 2006**Amendments to the Claims:**

Please cancel claims 4, 7, 8, 10-20, 25, and 29-31 without prejudice and amend the claims as shown in the following:

**Claim 1 (Previously Presented):** A modular electroless processing system, comprising:  
an interface section having a substrate transfer robot positioned thereon; and  
an electroless processing module positioned in communication with the interface section, the electroless processing module comprising:  
a processing enclosure;  
an electroless activation cell positioned in the enclosure;  
an electroless deposition cell positioned in the enclosure; and  
an enclosure robot configured to transfer substrates between the activation cell and the deposition cell.

**Claim 2 (Previously Presented):** The modular electroless processing system of claim 1, wherein the electroless activation cell and the electroless deposition cell comprise face up processing cells.

**Claim 3 (Previously Presented):** The modular electroless processing system of claim 2, wherein the activation cell and the deposition cell each comprise:  
a rotatable substrate support member configured to support a substrate in a configuration such that a production surface of the substrate is facing away from the substrate support member; and  
a fluid dispensing arm movably positioned to dispense a processing fluid onto the production surface of the substrate.

**Claim 4 (Canceled)**

**Claim 5 (Previously Presented):** The modular electroless processing system of claim 1, further comprising at least one substrate cleaning cell positioned in communication with the interface section.

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**Claim 6 (Previously Presented):** The modular electroless processing system of claim 5, wherein the at least one substrate cleaning cell comprises at least one of a spin rinse dry cell and a substrate bevel clean cell.

**Claims 7-8 (Canceled)**

**Claim 9 (Previously Presented):** The modular electroless processing system of claim 1, wherein the electroless processing module is removable from the interface section.

**Claims 10-20 (Canceled)**

**Claim 21 (Previously Presented):** An electroless processing system, comprising:  
a factory interface having a substrate transfer robot positioned therein, the factory interface being configured to communicate with at least one substrate containing cassette; and

at least two substrate processing modules in detachable communication with the factory interface, each of the at least two substrate processing modules including a pretreatment/post treatment cell and an electroless processing cell.

**Claim 22 (Previously Presented):** The electroless processing system of claim 21, wherein the substrate transfer robot comprises a linear track-type robot configured to access each of the substrate processing modules.

**Claim 23 (Previously Presented):** The electroless processing system of claim 21, wherein the at least two substrate processing modules further comprises a second substrate transfer robot positioned therein, the second substrate transfer robot being configured to transfer substrates between the substrate transfer robot in the factory interface, the pretreatment/post treatment cell, and the electroless processing cell.

**Claim 24 (Previously Presented):** The electroless processing system of claim 21, wherein the pretreatment/post treatment cell comprises a fluid processing cell configured to conduct at least one of rinsing, cleaning, edge bead removal, and spin rinse drying.

**Claim 25 (Canceled)**

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**Claim 26 (Previously Presented):** The electroless processing system of claim 21, wherein the at least two substrate processing modules are interchangeable.

**Claim 27 (Previously Presented):** The electroless processing system of claim 21, wherein the pretreatment/post treatment cells are interchangeable within the processing system.

**Claim 28 (Previously Presented):** The electroless processing system of claim 21, wherein the substrate processing cells are interchangeable within the processing system.

**Claims 29-31 (Canceled)**